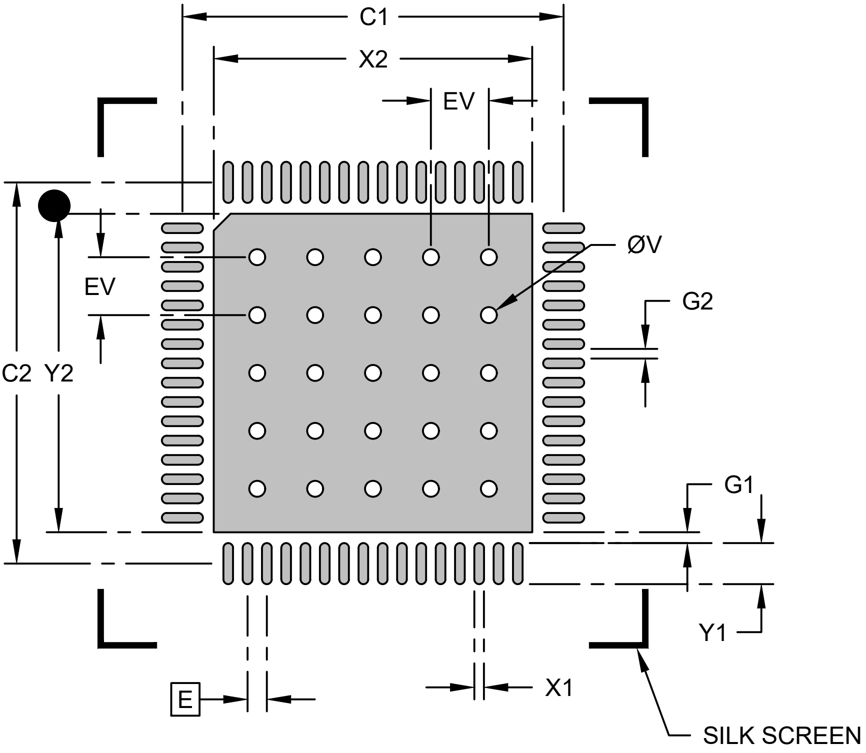
64-Lead Very-Thin Quad Flatpack No-Lead Package (8PW) - 8x8x0.9 mm Body [VQFN] With 6.5x6.5 mm Exposed Pad and Stepped Wettable Flanks

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

		Units	MILLIMETERS		
		Dimension Limits	MIN	NOM	MAX
Contact Pitch	E			0.40	
Center Pad Width	X2				6.60
Center Pad Length	Y2				6.60
Contact Pad Spacing	C1			7.90	
Contact Pad Spacing	C2			7.90	
Contact Pad Width (Xnn)	X1				0.20
Contact Pad Length (Xnn)	Y1				0.85
Contact Pad to Center Pad (Xnn)	G1		0.23		
Contact Pad to Contact Pad (Xnn)	G2		0.20		
Thermal Via Diameter	V			0.33	
Thermal Via Pitch	EV			1.20	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. The theoretically exact value is shown without tolerances.
2. For best soldering results, please refer to the current industry standard IPC-7093.